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PATENT ASSIGNMENT COVER SHEET

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07/13/2015

07/05/2015

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
YASUYUKI SEKIMOTO		06/29/2015
HIDEKIYO TAKAOKA		07/01/2015
SHIGEO NISHIMURA		07/01/2015

MINORU UESHIMA

TOHRU KURUSHIMA

RECEIVING PARTY DATA

Name:	MURATA MANUFACTURING CO., LTD.
Street Address:	10-1 HIGASHIKOTARI 1-CHOME
City:	NAGAKAKYO-SHI, KYOTO-FU
State/Country:	JAPAN
Postal Code:	617-8555
Name:	SENJU METAL INDUSTRY CO., LTD.
Street Address:	23 SENJUHASHIDOCHO
City:	ADACHI-KU, TOKYO
State/Country:	JAPAN
Postal Code:	120-8555

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	14809533	

CORRESPONDENCE DATA

	(212)484-3990 o the e-mail address first; if that is unsuccessful, it will be sent d; if that is unsuccessful, it will be sent via US Mail.
Phone:	2124843900
Email:	patentdocket@arentfox.com
Correspondent Name:	RICHARD LACAVA
Address Line 1:	1675 BROADWAY
Address Line 2:	ARENT FOX
Address Line 4:	NEW YORK, NEW YORK 10019

ATTORNEY DOCKET NUMBER:	036470.00050
NAME OF SUBMITTER:	RICHARD LACAVA
SIGNATURE:	/Richard LaCava/
DATE SIGNED:	07/27/2015
Total Attachments: 5 source=036470-00050ADS#page1.tif source=036470-00050ADS#page2.tif source=036470-00050ADS#page3.tif source=036470-00050ADS#page4.tif source=036470-00050ADS#page5.tif	

itle of vention	METHOD OF FORMING SOLDER BUMP, AND SOLDER BUMP
As the belo	w named inventor, i declare that:
This declar	ation is directed to:
	The attached application, or
	United States application or PCT international application number
The above	-identified application was made or authorized to be made by me.
l believe th	at I am the original inventor or an original joint inventor of a claimed invention in the application.
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The under made or e	signed hereby covenants that no assignment, sale, agreement or encumbrance has been or will be ntered into which would conflict with this assignment.
are believe statement	ents made herein of my own knowledge are true, all statements made herein on information and belief ed to be true, and further that these statements were made with the knowledge that willful false s and the like are punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) both, and may jeopardize the validity of the application or any patent issuing thereon.
LEGAL N	AME OF INVENTOR
	Yasuyuki Sekimoto Date: June 29, 2015

DEC	LARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT
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LEGAL NA	ME OF INVENTOR
Inventor:	Hidekiyo Takaoka Date: July 1, 2015
Signature:	Hidekiyo Takaoka.

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LEGAL NA	AME OF INVENTOR
Inventor:	Shigeo Nishimura Date: July 1, 2015
	Shigeo Nishimura

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LEGAL N	AME OF INVENTOR
Inventor:	Minoru Ueshima Date: July 13, 20/5
	Manny Venland

AFDOCS/12183797.1

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RECORDED: 07/27/2015